Topical Collection

Virtual and Augmented Reality Systems

Message from the Collection Editors

This Special Issue is an opportunity for the scientific community to present recent high-quality research works regarding any branch of virtual and augmented reality. Topics of interest include but are not limited to:

- Human–computer interactions in the virtual and augmented environment;
- 3D user interaction in virtual and augmented space;
- Shared VR and AR technologies;
- Untact technologies in virtual and augmented space;
- Graphical simulation for VR and AR systems;
- AI-based technologies for VR and AR systems;
- Immersive analytics and visualization;
- Multiuser and distributed systems;
- Graphical advancements in virtual and augmented space

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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